

Appl. No. 10/664,585  
Amdt. Dated January 17, 2006  
Reply to Office Action of October 17, 2005

Attorney Docket No. 81751.0066  
Customer No.: 26021

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently amended): A semiconductor device comprising:
  - a die pad;
  - a semiconductor chip having an electrode and bonded to the die pad;
  - an inner lead having a sloping section sloping upward and outward from the semiconductor chip, wherein a surface of the die pad which the semiconductor chip is bonded faces upward;
  - a wire electrically connecting the inner lead to the electrode;
  - a sealing section sealing the inner lead, the semiconductor chip, and the wire; and
  - an outer lead extending outward from the sealing section;
  - wherein the wire is bonded to the sloping section of the inner lead, and wherein a portion of the inner lead is higher than the semiconductor chip.

2-4. (Cancelled).

5. (Original): The semiconductor device as defined in claim 1, wherein the inner lead further has a second sloping section sloping downward and outward from a higher end of the sloping section.

6. (Original): The semiconductor device as defined in claim 1, wherein the inner lead further has a portion extending in a horizontal direction and connected to the outer lead.

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7. (Previously Presented): The semiconductor device as defined in claim 1, wherein a bonding position between the wire and the inner lead is lower than the position of the electrode.

8. (Cancelled).

9. (Original): The semiconductor device as defined in claim 1, wherein a surface of the die pad opposite to the semiconductor chip is exposed from the sealing section.

10. (Original): A circuit board on which the semiconductor device as defined in claim 1 is mounted.

11. (Original): An electronic instrument comprising the semiconductor device as defined in claim 1.

12-20. (Cancelled).

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21. (Currently amended): A semiconductor device comprising:

- an inner lead having a first sloping section sloping upward and outward from the semiconductor chip, the inner lead having a second sloping section sloping downward and outward from a higher end of the first sloping section, when wherein a surface of the die pad which the semiconductor chip is bonded faces upward;
- a die pad;
- a semiconductor chip having an electrode and bonded to the die pad;
- a wire electrically connecting the inner lead to the electrode;
- a sealing section sealing the inner lead, the semiconductor chip, and the wire; and
- an outer lead extending outward from the sealing section, and wherein a portion of the inner lead is higher than the semiconductor chip.